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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Shay A. Dani et al.

Title: HEAT DISSIPATING DEVICE WITH PRESELECTED DESIGNED INTERFACE FOR THERMAL INTERFACE MATERIALS

Docket No.: 884.945US1

Filed: June 30, 2003

Examiner: Unknown

Serial No.: 10/612834

Due Date: N/A

Group Art Unit: 3743

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- A return postcard.
- A Communication Concerning Related Applications (1 pg.).
- An Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 3 cited documents.

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: J. M. Kalis

Atty: Janal M. Kalis

Reg. No. 37,650

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 20 day of May, 2004.

Name

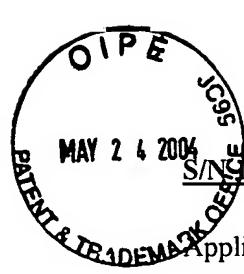
Kacia Lee

Signature

Kacia Lee

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)



PATENT

S/N 10/612834

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Ashay A. Dani et al.	Examiner: Unknown
Serial No.:	10/612834	Group Art Unit: 3743
Filed:	June 30, 2003	Docket: 884.945US1
Title:	HEAT DISSIPATING DEVICE WITH PRESELECTED DESIGNED INTERFACE FOR THERMAL INTERFACE MATERIALS	
Assignee:	Intel Corporation	Customer No.: 21186

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10/405095	March 31, 2003	884.827US1	HEAT SINK WITH PREATTACHED THERMAL INTERFACE MATERIAL AND METHOD OF MAKING SAME
10/607738	June 26, 2003	884.832US1	MULTI-LAYER POLYMER-SOLDER HYBRID THERMAL INTERFACE MATERIAL FOR INTEGRATED HEAT SPREADER AND METHOD OF MAKING SAME

Respectfully submitted,

ASHAY A. DANI ET AL.

By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Attorneys for Intel Corporation
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6976

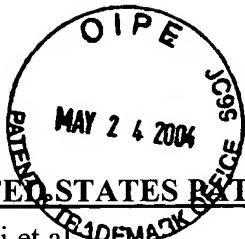
Date 20 May 04 By J. M. Kalis
Jaral M. Kalis
Reg. No. 37,650

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Name: KACIA LEE

Signature: Kacia Lee

S/N 10/612834



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Ashay A. Dani et al.	Examiner:	Unknown
Serial No.:	10/612834	Group Art Unit:	3743
Filed:	June 30, 2003	Docket:	884.945US1
Title:	HEAT DISSIPATING DEVICE WITH PRESELECTED DESIGNED INTERFACE FOR THERMAL INTERFACE MATERIALS		
Assignee:	Intel Corporation	Customer No:	21186

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

INFORMATION DISCLOSURE STATEMENT

Serial No : 10/612834

Filing Date: June 30, 2003

Title: HEAT DISSIPATING DEVICE WITH PRESELECTED DESIGNED INTERFACE FOR THERMAL INTERFACE MATERIALS

Assignee: Intel Corporation

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Dkt: 884.945US1 (INTEL)

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

ASHAY A. DANI ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Attorneys for Intel Corporation
P.O. Box 2938
Minneapolis, Minnesota 55402
(612) 373-6976

Date 20 May 04

By Janal M. Kalis
Janal M. Kalis
Reg. No. 37,650

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 20 day of May, 2004.

Name

KACIA LEE

Signature

Kacia Lee

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(Use as many sheets as necessary)

Sheet 1

Complete if Known

Application Number	10/612834
Filing Date	June 30, 2003
First Named Inventor	Dani, Ashay
Group Art Unit	3743
Examiner Name	Unknown

Attorney Docket No: 884.945US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-6,504,242	01/07/2003	Deppisch, Carl L., et al.	257	707	11/15/2001

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		CHANG, CHIN-AN , "Enhanced Cu-Teflon adhesion by presputtering treatment: Effect of surface morphology changes", <u>Applied Physics Letters</u> , 51(16), (October 19, 1987), 1236-1238	
		PERRINS, L E., et al., "Mechanism for the adhesion of electroplated copper to polypropylene", <u>Plastics and Polymers</u> , 39(144), (December 1971), 391-397	

EXAMINER**DATE CONSIDERED**